PRESENTATION HIGHLGHTS @ISSCC2021

TITLE :

A 12nm Autonomous Driving Processor with 60.4TOPS, 13.8TOPS/W CNN Executed by Task-separated ASIL D Control

February 17, 2021 Automotive SoC Development Division Automotive Solution Business Unit Renesas Electronics Corporation ISSCC online QA session: US PST: Feb 16, 8:30-9:30

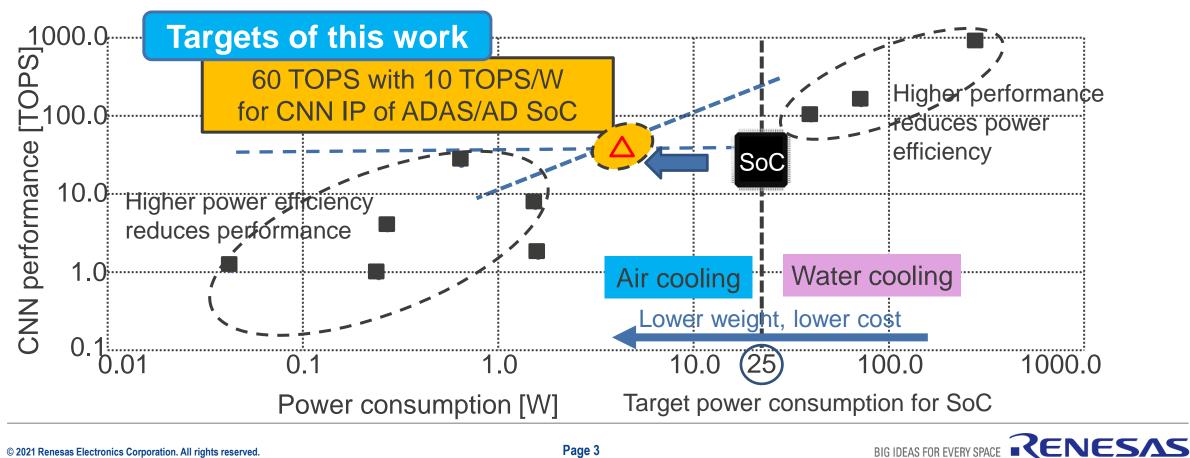


EXECUTIVE SUMMARY

- Renesas developed the processor technologies for automotive systems-on-chip (SoCs) used in applications such as advanced driver assistance systems (ADAS) and self-driving systems that aim to optimize both performance and power efficiency while supporting a high level of functional safety.
- The new technologies developed by Renesas and implemented in the R-Car V3U are described below.
 - 1. Development of high-performance CNN hardware accelerator with superior power efficiency
 - 2. Development of safety mechanisms for ASIL D systems capable of self-diagnosis
 - 3. Development of a support mechanism for freedom from interference (FFI) between software tasks
- Renesas presented these achievements at International Solid-State Circuits Conference 2021 (ISSCC 2021), which is taking place February 13 to 22, 2021.

BACKGROUND OF DEVELOPMENT (1) MOTIVATION - CNN PERFORMANCE/WATT TARGETS

- Require optimization for both high DL performance and lower power efficiency
- CNN 60TOPS with 10 TOPS/W is the sweet spot for ADAS/AD systems

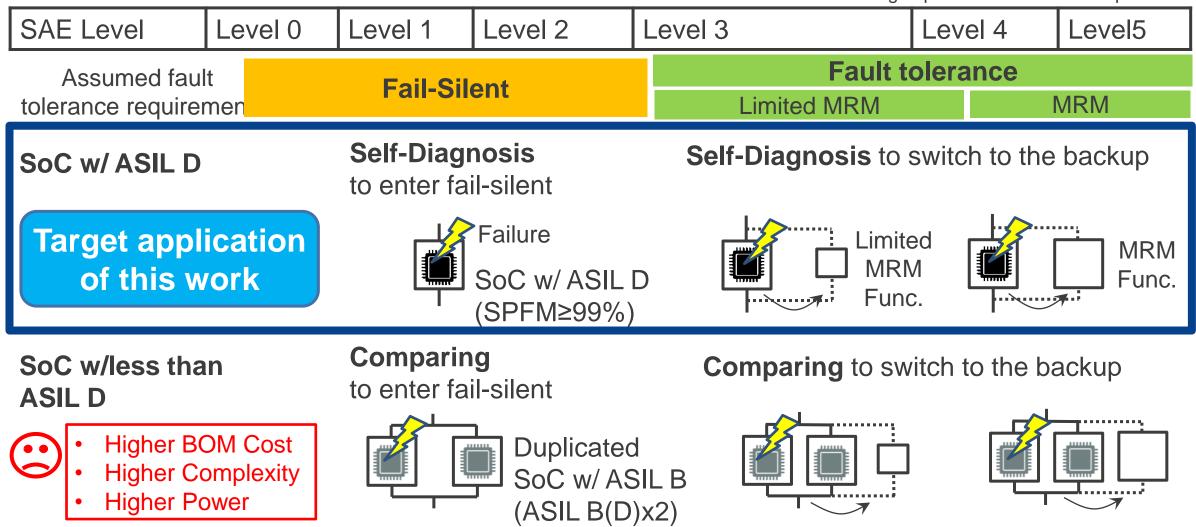


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BACKGROUND OF DEVELOPMENT (2) MOTIVATION - BENEFIT OF SOC W/ ASIL D* OFFERING

* Referring to process and metrics capabilities

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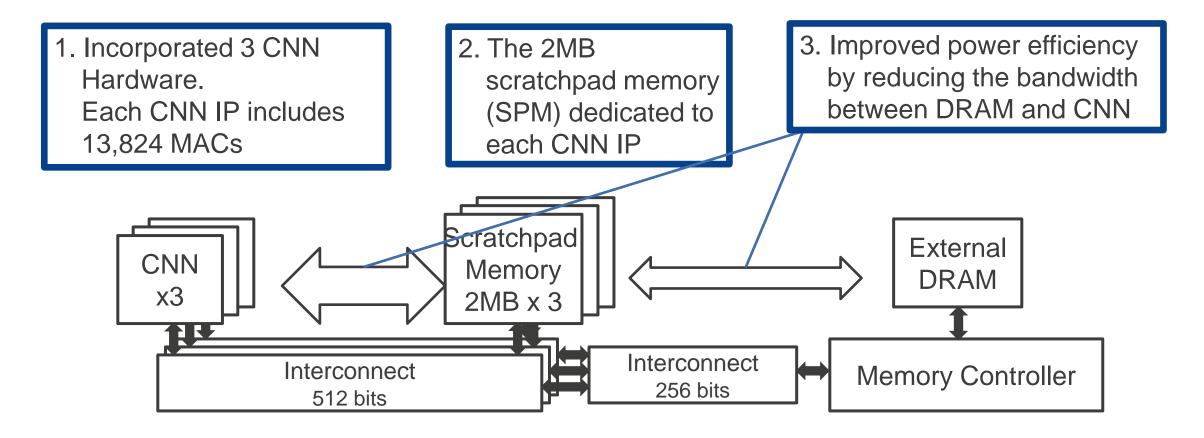
OVERVIEW @ ISSCC 2021

Renesas Develops Automotive SoC Technologies with CNN Accelerator Cores and ASIL D Control Combining World-Class Performance and Power Efficiency

- Renesas has developed a convolutional neural network (CNN) hardware accelerator core that delivers a world-class combination of deep learning performance of 60.4 trillion operations per second (TOPS) and a power efficiency of 13.8 TOPS/W.
- 2. Renesas has developed sophisticated safety mechanisms for fast detecting and response of random hardware failures.
- 3. Renesas has developed a mechanism that allows software tasks with different safety levels to operate in parallel on SoC without interfering with each other.

DEVELOPED TECHNOLOGY 1 CNN HARDWARE WITH HIGH PERFORMANCE AND EFFICIENCY

• Achieved performance 60 TOPS with efficiency of 10 TOPS/W



DEVELOPED TECHNOLOGY 2 SAFETY MECHANISMS CAPABLE OF SELF-DIAGNOSIS FOR ASIL D SYSTEMS

• Safety mechanisms for fast detecting and response of random hardware failures occurring in the SoC overall.

Green squares and

ASIL D target module.

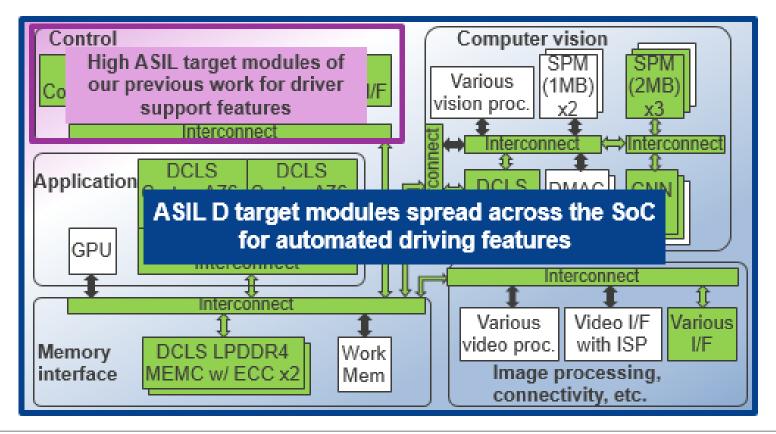
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arrows indicate

• Achieved both extremely high failure detection rate and reduced power consumption by combining safety mechanisms suited to specific target functions.

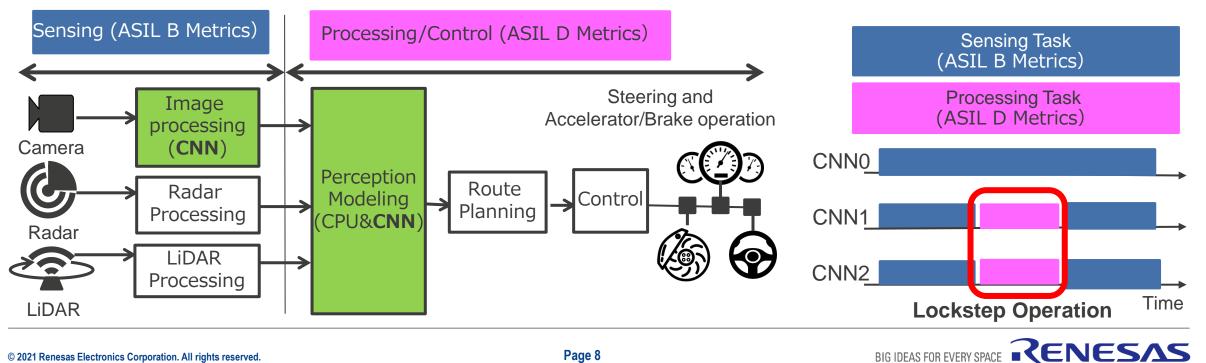
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DEVELOPED TECHNOLOGY 2 SAFETY MECHANISMS FOR CNN ACCELERATOR

- The CNN accelerator is used for ASIL B image processing input from cameras and ASIL D perception modeling from the results input from each sensor.
- Most of the processing performed by the CNN accelerator is ASIL B image recognition processing.
- Rather than configuring all CNN accelerators redundantly, only the ASIL D periphery perception modeling process is performed in lockstep operation to achieve ASIL D metrics with low power consumption.



DEVELOPED TECHNOLOGY 2 HARDWARE SUPPORTED SOFTWARE LOCKSTEP

Implemented "Hardware Supported Software Lockstep" that can execute lockstep process for any period of time using CNN accelerator 1 (CNN1), CNN accelerator 2 (CNN2), and Lockstep DMAC.

Execute by 3 Step

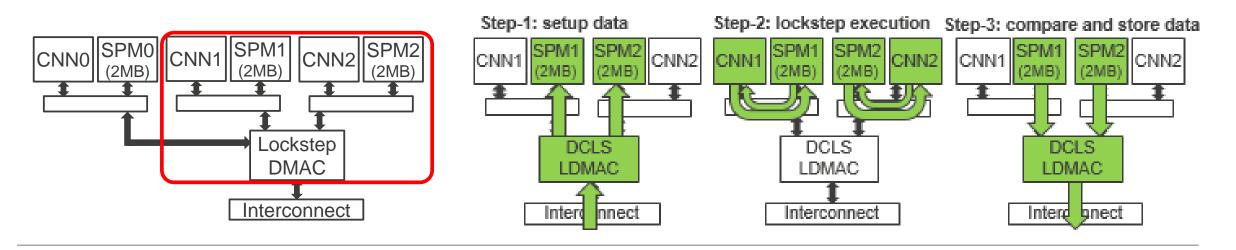
Step-1: LDMAC starts data transfer using the lockstep read descriptor.

=> LDMAC reads data from DRAM and stores in SPM1 and SPM2 both.

Step-2: CNN1 and CNN2 start the same operation.

Step-3: LDMAC stars data transfer using the lockstep write descriptor.

=> LDMAC compares with SPM2 data when transferring SPM1 data to DRAM.

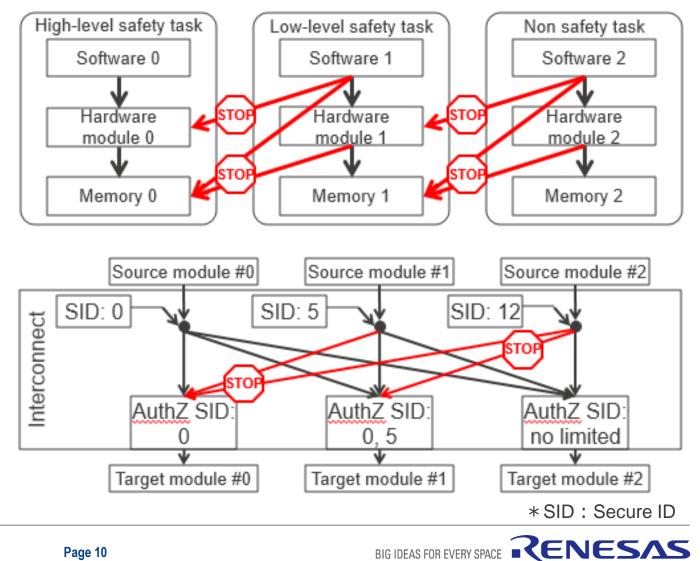


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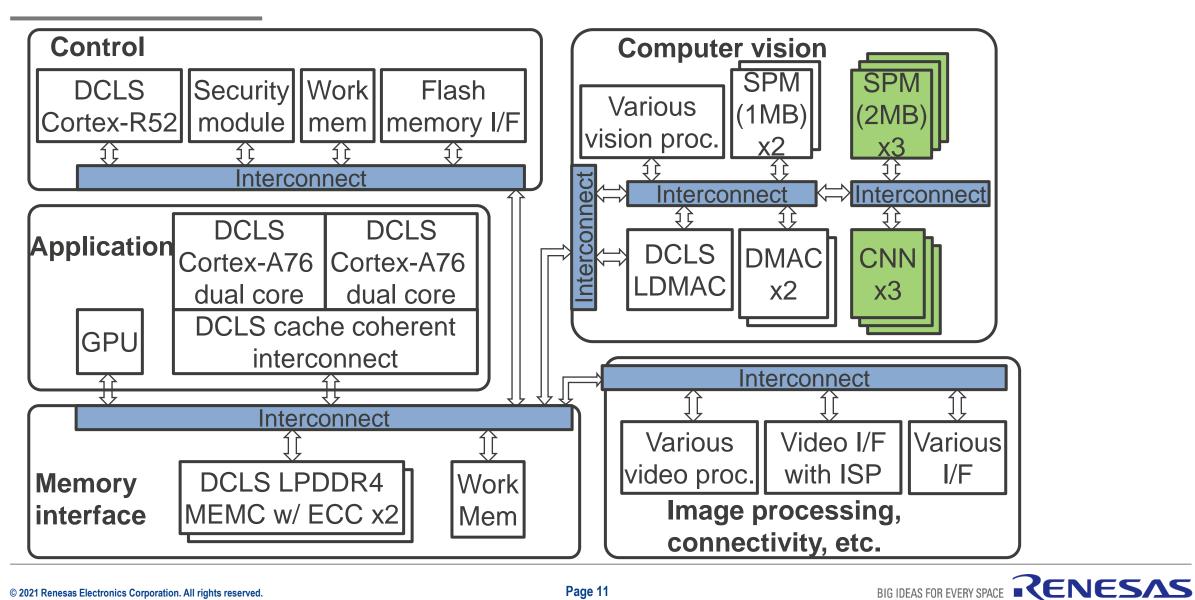
DEVELOPED TECHNOLOGY 3 SUPPORT MECHANISM FOR FREEDOM FROM INTERFERENCE (FFI)

Lower ASIL level tasks must not interfere with high-level safety tasks.

Support mechanism for Freedom From Interference(FEI) blocks unauthorized transactions and returned as the error response by monitoring all transactions in the interconnect of SoC



Architecture Overview of R-Car V3U



R-Car V3U Overview

	Process	12nm
DDR I/F Vision	Voltage	0.80V (Other than CPU and GPU) 0.85V (CPU,GPU)
CNN1 Proc. ISP	Chip size	230.46mm ²
	On chip SRAM	~ 41.6MB
CNN0 2MB x3 Misc x3 DCLS Cortex-A76 Dual Core 1 DCLS Dual Core 1	Performance	1.8GHz Dual core lockstep (DCLS) ARM Cortex- A76 dual core x2 1GHz DCLS safety processor LPDDR4-4266 16bit x8 600MHz GP-GPU
	Key accelerators	Theoretical maximum 66TOPS CNN hardware 480Mpixel ISP x4, Image classification x8
	High speed interfaces	PCIe Gen4 x4, Gbit-EtherAVB x6 MIPI CSI-2 10Gbps x4, DSI 10Gbps x4
GPU DCLS Cortex-A76 Dual Core 0 DDR I/F	Functional safety	Process: ASIL D Metrics: SPFM≥99%/LFM≥90% enabled through on- chip measures allowing fast system fault tolerant time interval

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<APPENDIX> SAFETY MECHANISM FOR ASIL D TARGET

Domain	ASIL D Target Module	Applied Safety Mechanism
Control	Cortex-R52, Security module, Work mem, Flash memory I/F	Dual core lockstep, ECC/EDC, End- to-end protection
Memory	LPDDR4 memory controller	Dual core lockstep, ECC/EDC
Application	Cortex-A76, Cache coherent interconnect	Dual core lockstep, ECC/EDC
Computer vision	CNN, LDMAC, SPM(2MB)	Dual core lockstep, ECC/EDC, Hardware Supported Software Lockstep, Runtime test
Connectivity	PCIe, EAVB, CAN-FD, Flexray	End-to-end protection
Interconnect	All modules	End-to-end protection, Dual core lockstep, ECC/EDC